

Title (en)

ELECTROCHEMICAL COATING DEVICE AND METHOD

Title (de)

VORRICHTUNG UND VERFAHREN ZUR ELEKTROCHEMISCHEN BESCHICHTUNG

Title (fr)

PROCEDE ET DISPOSITIF DE REVETEMENT ELECTROCHIMIQUE

Publication

EP 1534880 B1 20070328 (DE)

Application

EP 01272605 A 20010924

Priority

- DE 0103676 W 20010924
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Abstract (en)

[origin: WO02053806A2] The invention relates to a device and method, with which it is possible to electrochemically deposit thin layers with a nearly homogeneous layer thickness on large-surface substrates having relatively high resistances. These thin layers are, for example, metal layers, metal oxide layers or semiconductor layers as well as layers consisting of conductive polymers that, for example, are deposited on transparent electrodes or semiconductor substrates. The counter-electrode for the substrate to be coated is divided into several electrode segments and voltages that differ from one another can be applied between each individual electrode segment and the substrate to be coated. This results in achieving a good homogeneity of the deposited thin layers with respect to thickness and physical properties.

IPC 8 full level

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